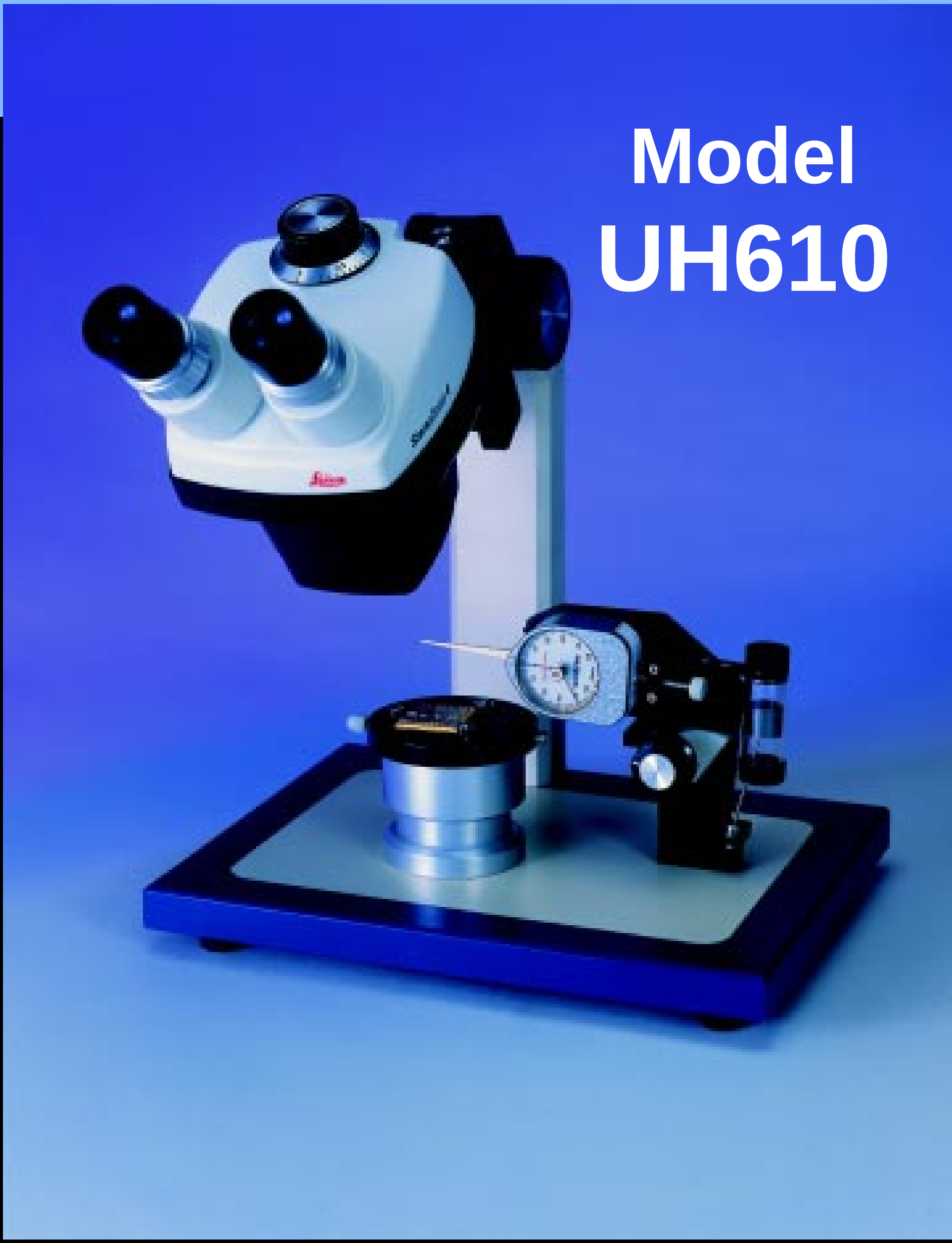
WIRE BOND PULL TESTER



Model UH610

Ultron Systems' Model UH610 Wire Bond Pull Tester provides a simple, low-cost solution for determining wire bond integrity. It is capable of accurate and reliable pull strength measurement in either destructive or non-destructive test modes. An easily adjustable independent Z-motion speed control allows variable pull test rates. Optional chucks are available to accommodate almost all types of packages. Test gauges are available in a variety of ranges to meet different requirements and can be quickly interchanged.

ULTRON SYSTEMS, INC.

OPTIONS

Stereo Microscope

Microscope Mount

Illuminator with power supply

Gauges

Pull Test Hooks

Chucks to accommodate almost any type of package

SPECIFICATIONS

Width:	**11”**
Depth:	**$8^{3}/_{8}$”**
Height :	**$11^{3}/_{8}$”**
Weight:	**7 lbs.**

Ultron Systems offers a complete line of adhesive plastic films for wafer/die handling. Please call for additional information and samples.

For additional information, please contact:

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